Restriction of Hazardous Substances in Electrical and Electronic Equipment (RoHS) Directive Statement

Ascom (Sweden) AB hereby declares that our products do not contain any of the restricted substances above the legal threshold limits as listed in directive 2011/65/EU and amendment 2015/863/EU on the restriction of hazardous substances in electrical and electronic equipment:

- Lead (Pb) ≤ 0.1%
- Mercury (Hg) ≤ 0.1%
- Cadmium (Cd) ≤ 0.01%
- Hexavalent Chromium (Cr^{6+}) ≤ 0.1%
- Polybrominated Biphenyls (PBB) ≤ 0.1%
- Polybrominated Diphenyl Ethers (PBDE) ≤ 0.1%
- Bis(2-ethylhexyl) phthalate (DEHP) ≤ 0.1%
- Butyl benzyl phthalate (BBP) ≤ 0.1%
- Dibutyl phthalate (DBP) ≤ 0.1%
- Diisobutyl phthalate (DIBP) ≤ 0.1%

In cases where restricted substances are present, they are used only in accordance with the applicable RoHS exemptions listed in Annex III and Annex IV of Directive 2011/65/EU and amendments.

Applicable RoHS Exemptions

Annex III Exemptions

7(a) – Lead in high-melting-temperature solders (≥ 85% Pb).

7(a)-I – Lead in high-melting-temperature solders for internal interconnections in semiconductor assembly (specific electrical criteria apply).

7(a)-II – Lead in high-melting-temperature die-attach solder where all the following apply:

- Thermal conductivity > 35 W/(m·K)
- Electrical conductivity > 4.7 MS/m
- Solidus temperature > 260 °C

7(a)-V – Lead in high-melting-temperature solders used as hermetic sealing material between:

1. Ceramic package/plug and metal case
2. Component terminations and internal sub-parts

7(b) – Lead in solders for servers, storage systems, and network infrastructure equipment for telecommunications.

7(c)-I (Amd. Delegated Directive (EU) 2025/2363) – Lead in glass or ceramic in electronic components (excluding dielectric ceramic in capacitors), such as in piezoelectronic devices or glass/ceramic matrix compounds.

7(c)-V (Amd. Delegated Directive (EU) 2025/2363) – Lead in glass or glass matrix compounds used for:

a. Protection/insulation in high-voltage diode beads and wafer glass layers
b. Hermetic sealing between ceramic, metal and/or glass
c. Bonding < 500 °C with viscosity $10^{13}.^{3}$ dPas
d. Resistive materials (1 Ω/sq to 100 MΩ/sq), excluding trimmer potentiometers
e. Chemically modified glass for MCPs, CEMs and RGPs

7(c)-VI (Amd. Delegated Directive (EU) 2025/2363) – Lead in ceramic materials used for:

a. Piezoelectric PZT ceramics
b. Ceramics with positive temperature coefficient (PTC

31 – Lead in soldering materials in mercury-free flat fluorescent lamps for LCDs, design, or industrial lighting.

33 – Lead in solders for thin copper wires (≤ 100 µm) in power transformers.

38 – Cadmium and cadmium oxide in thick-film pastes used on aluminium-bonded beryllium oxide.

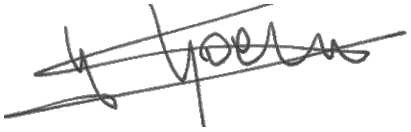
39(b) – Cadmium in downshifting semiconductor nanocrystal quantum dots on LED chips (< 5 µg Cd per mm^2; max 1 mg/device).

Annex IV (Medical Devices)

16 – Mercury in very-high-accuracy capacitance and loss measurement bridges, and in high-frequency RF switches/relays (≤ 20 mg per device).

19 – Lead in Liquid Crystal on Silicon (LCoS) displays.

Göteborg, 19 December 2025



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